
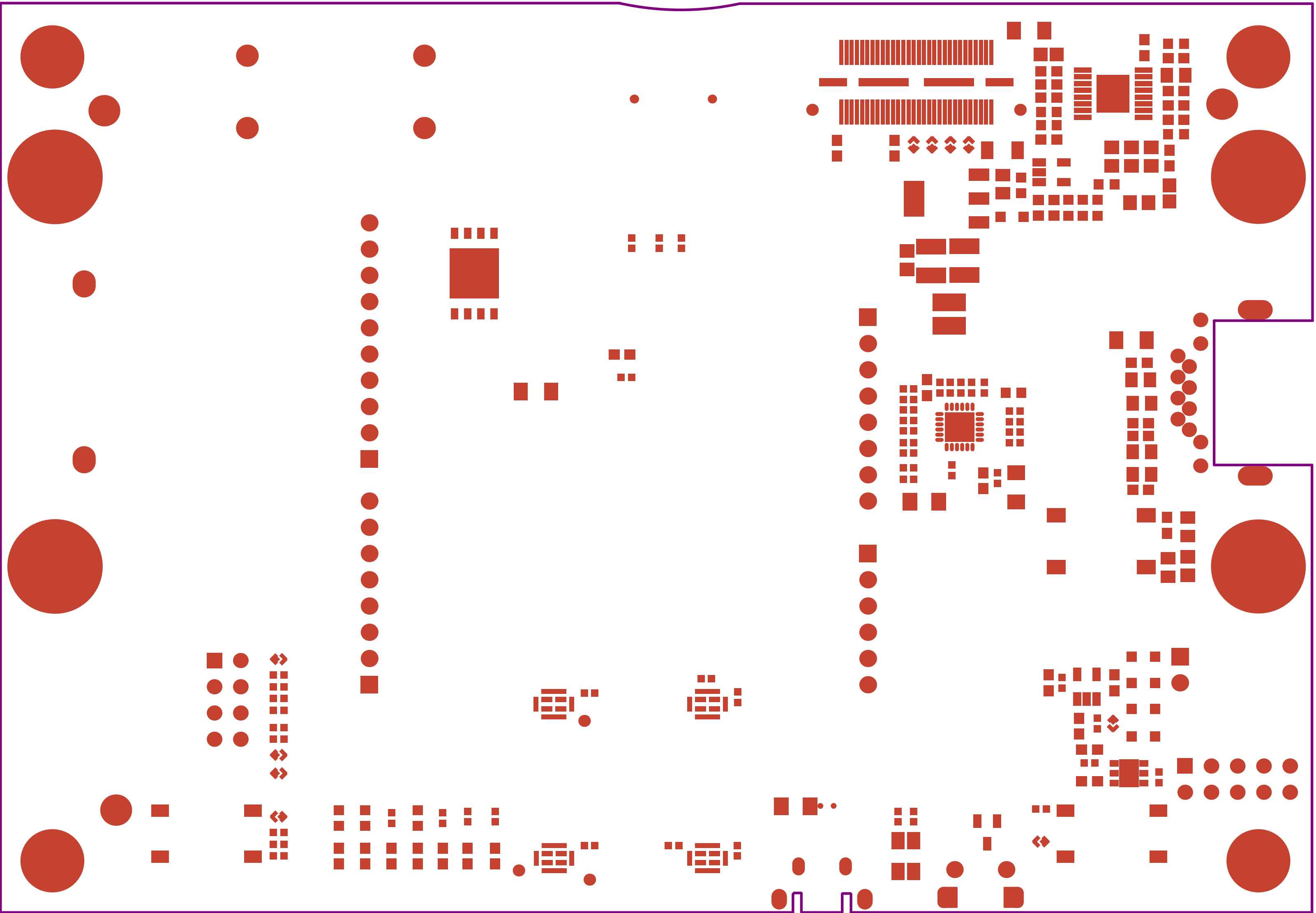
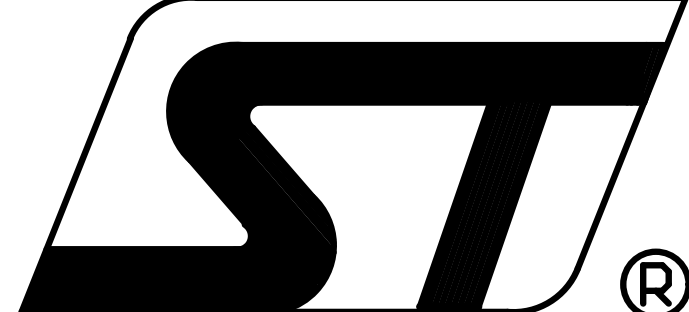
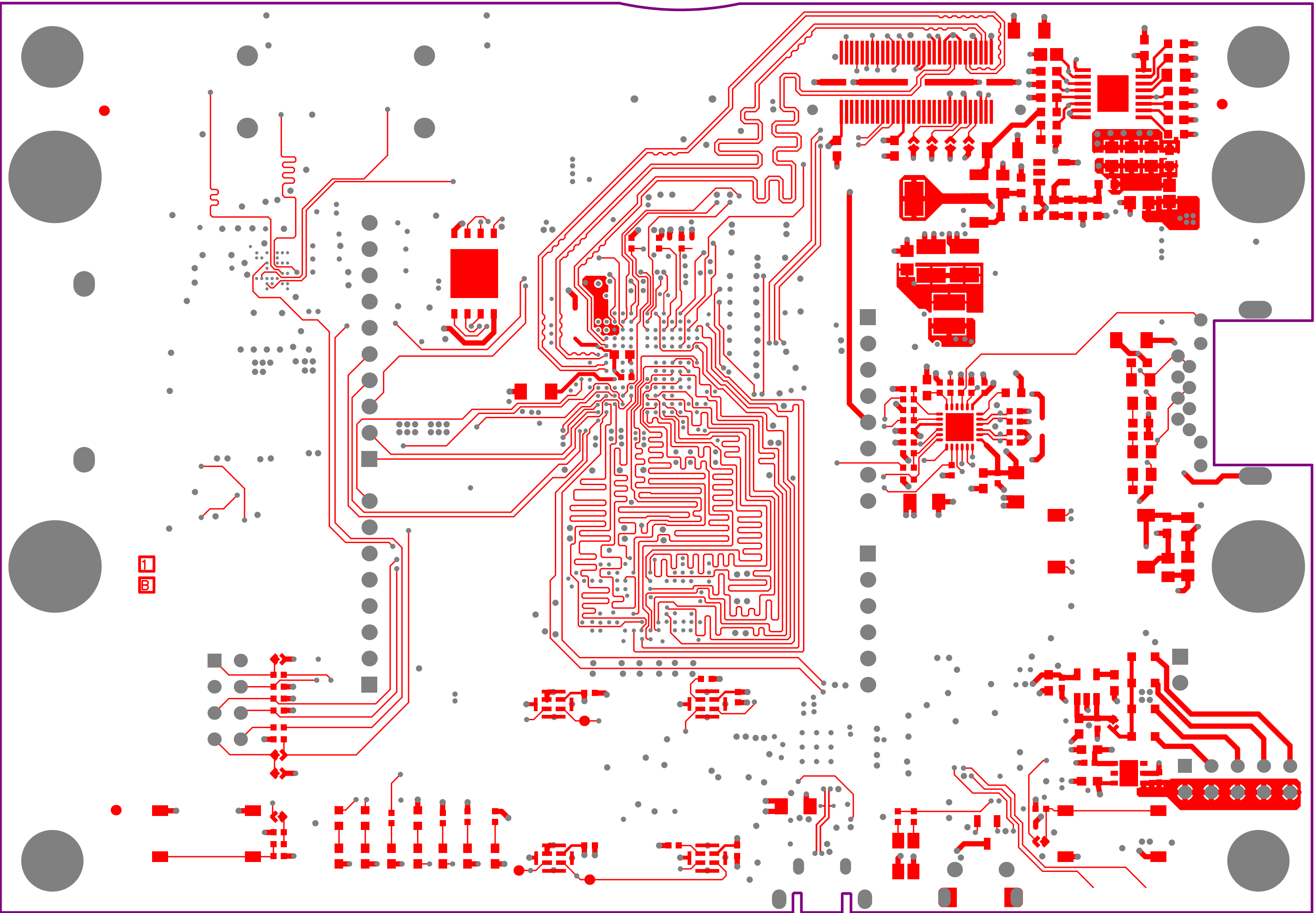



Designator1

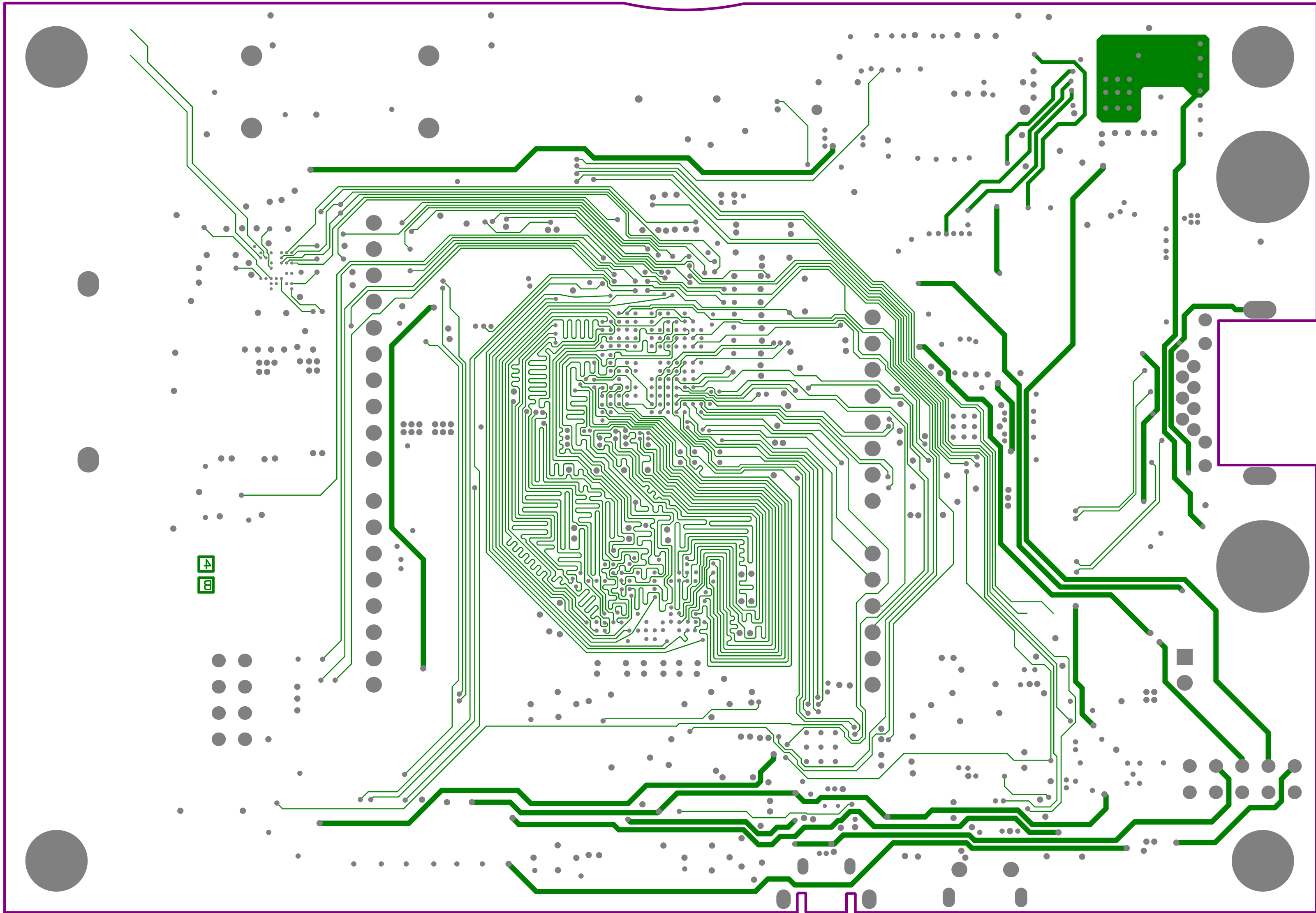
Project: STM32F769I-DISCO		
Layer: Top Overlay	Gerber: .GTO	
Variant: F769I	Ref: MB1225	
Date: 01/06/2020	Rev: C	




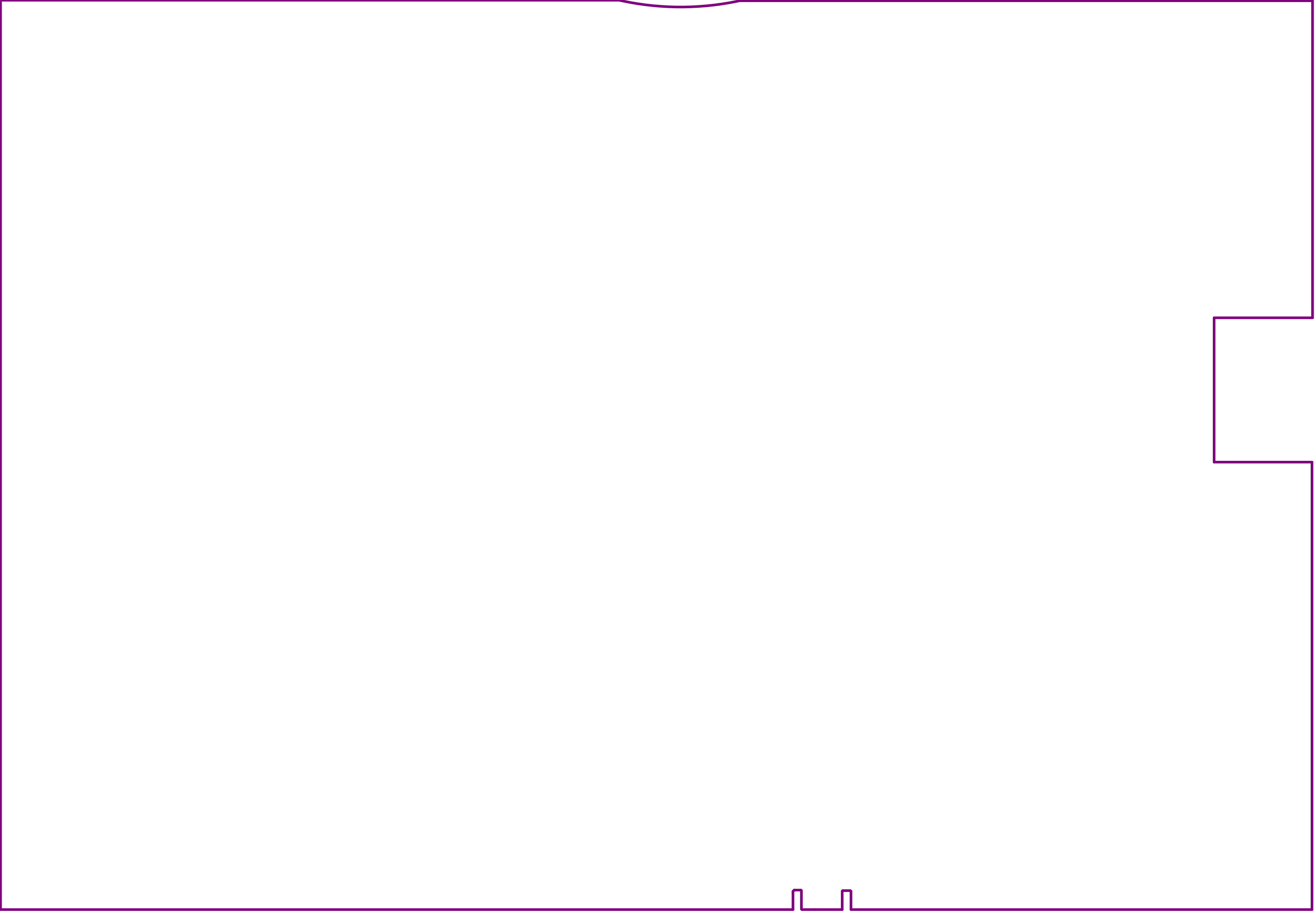
Project: STM32F769I-DISCO		
Layer: Top Solder	Gerber: .GTS	
Variant: F769I	Ref: MB1225	
Date: 01/06/2020	Rev: C	




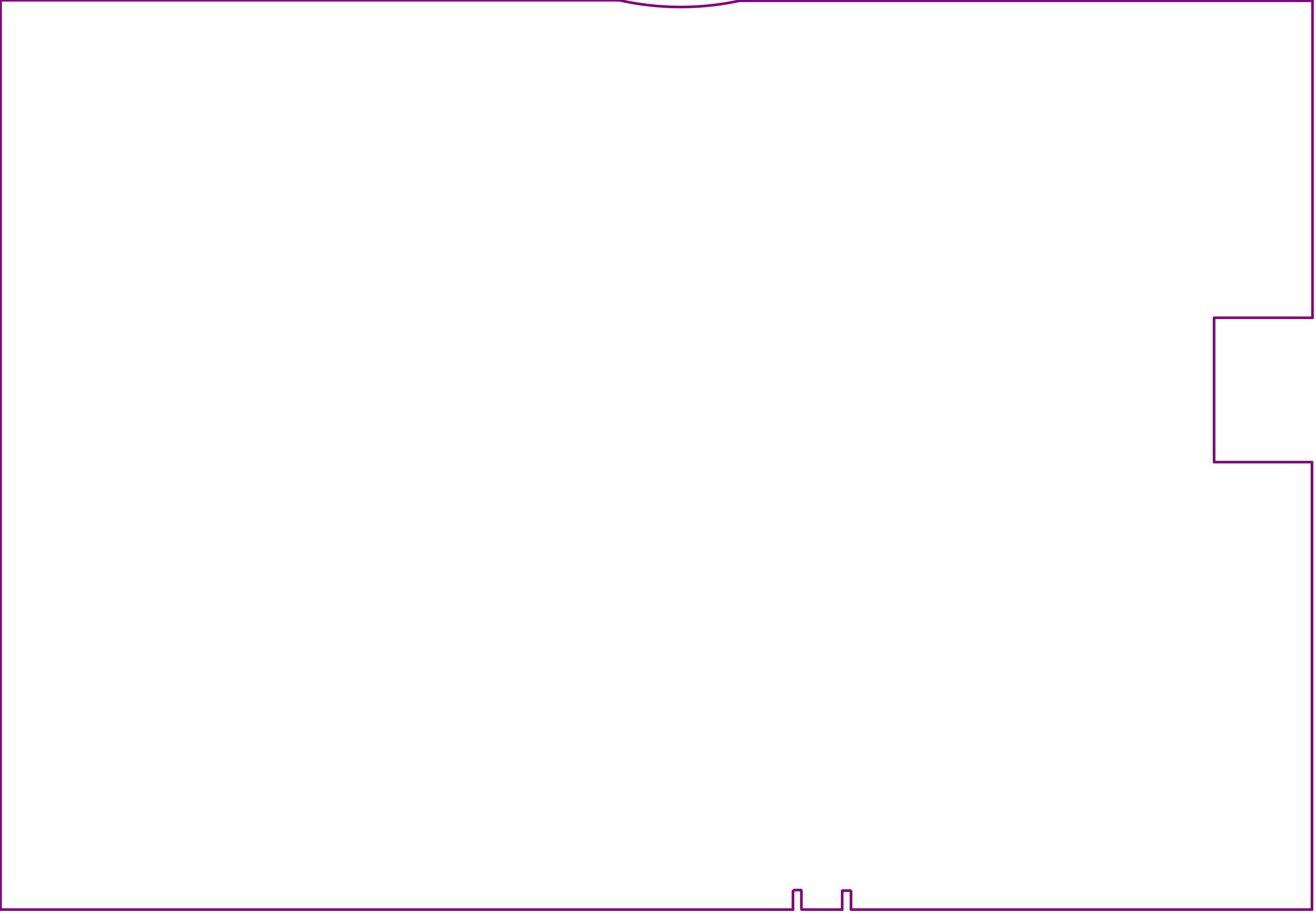
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Layer: Top Layer	Gerber: .GTL	
Variant: F769I	Ref: MB1225	
Date: 01/06/2020	Rev: C	




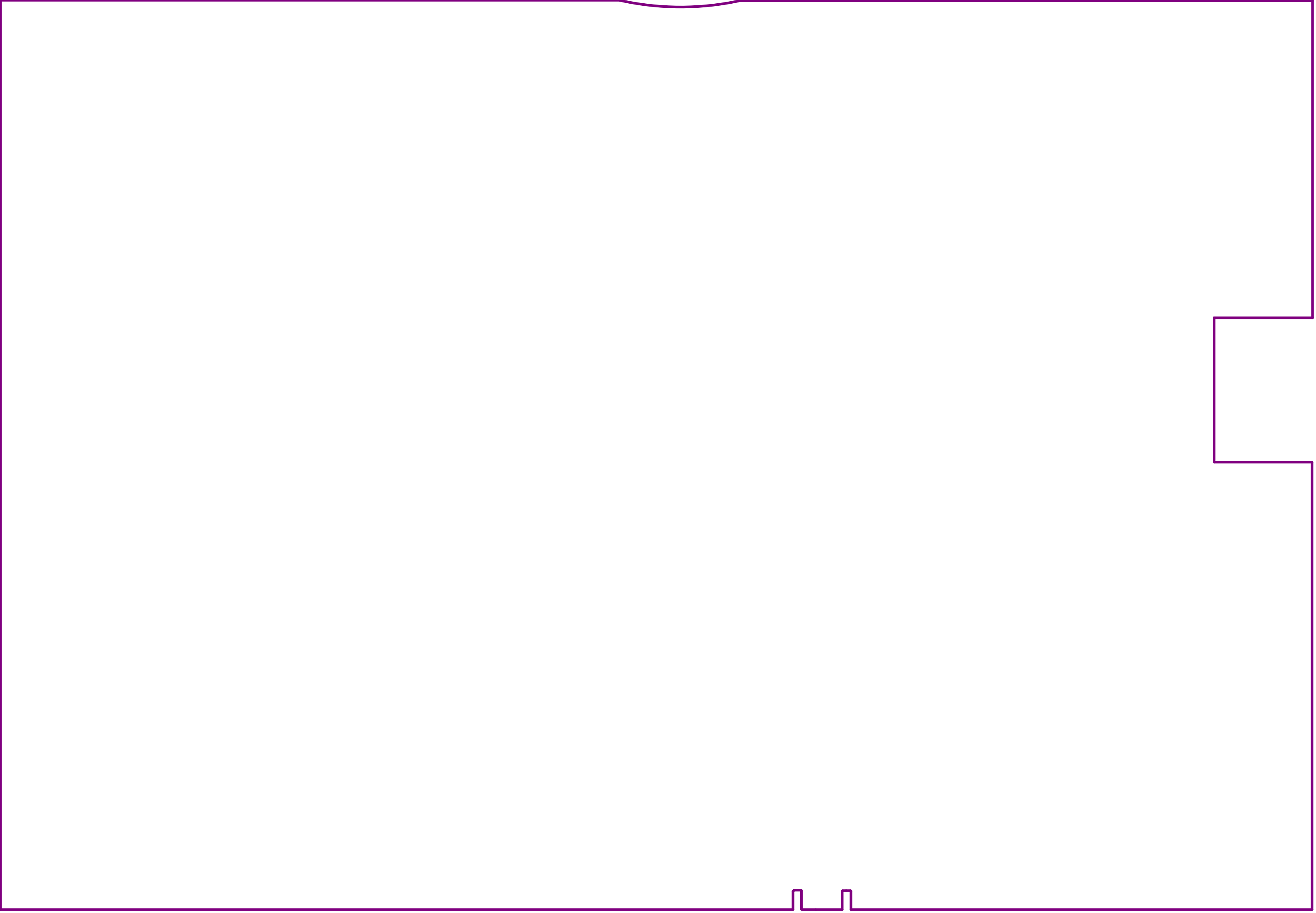
Project: STM32F769I-DISCO		
Layer: L4_SIG	Gerber: .G1	
Variant: F769I	Ref: MB1225	
Date: 01/06/2020	Rev: C	




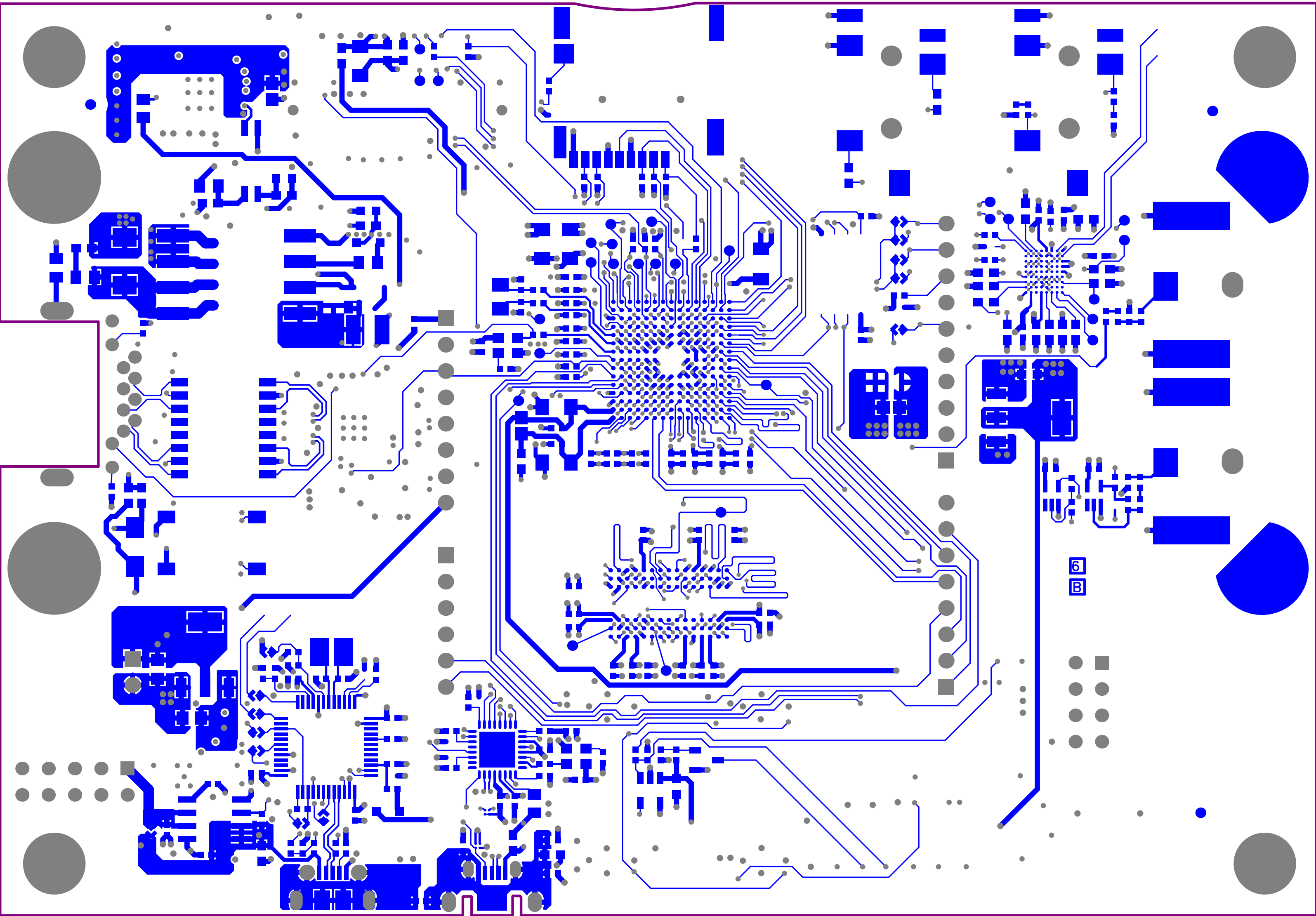
Project: STM32F769I-DISCO		
Layer:	Gerber:	
Variant: F769I	Ref: MB1225	
Date: 01/06/2020	Rev: C	

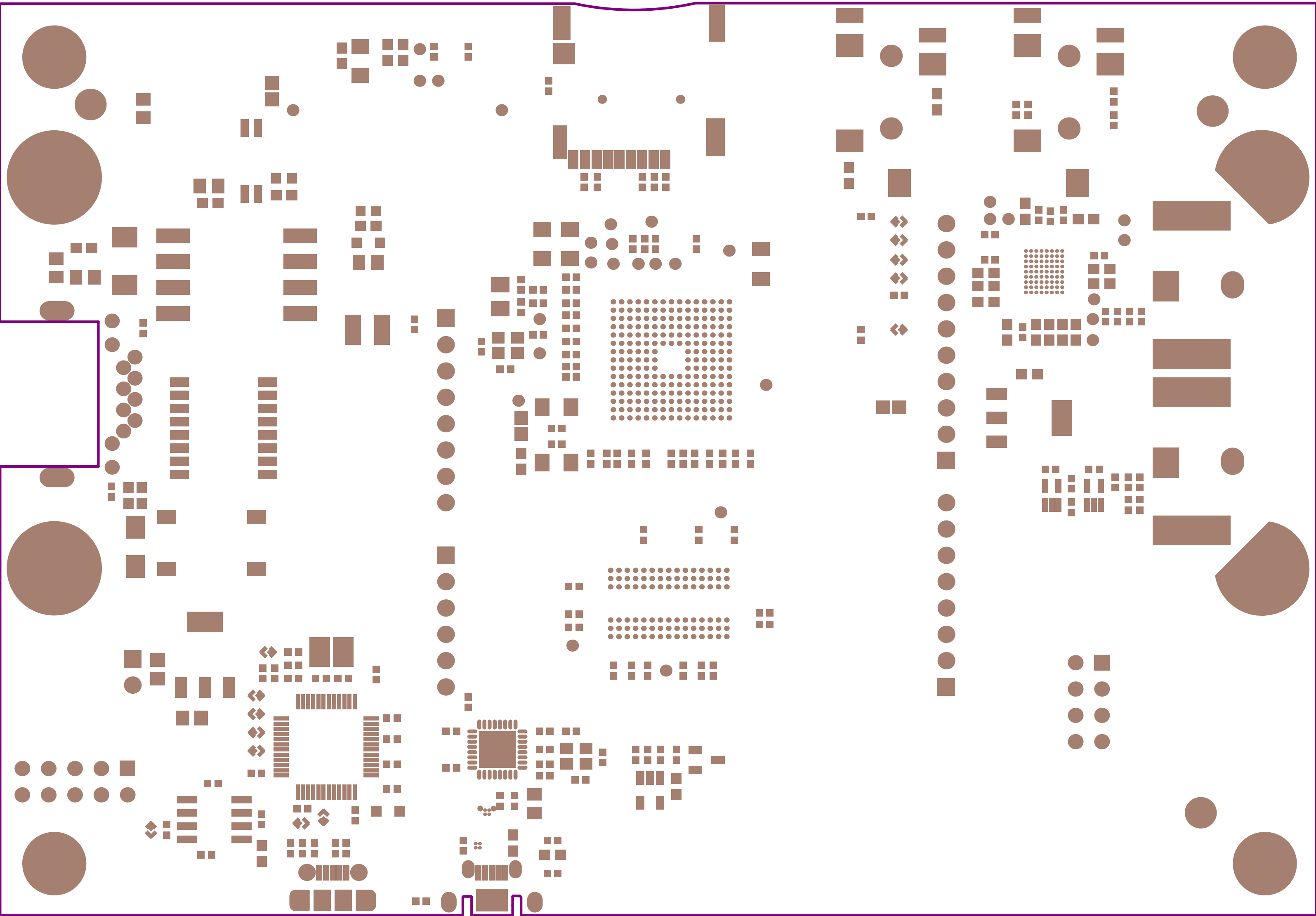



Project: STM32F769I-DISCO		
Layer:	Gerber:	
Variant: F769I	Ref: MB1225	
Date: 01/06/2020	Rev: C	

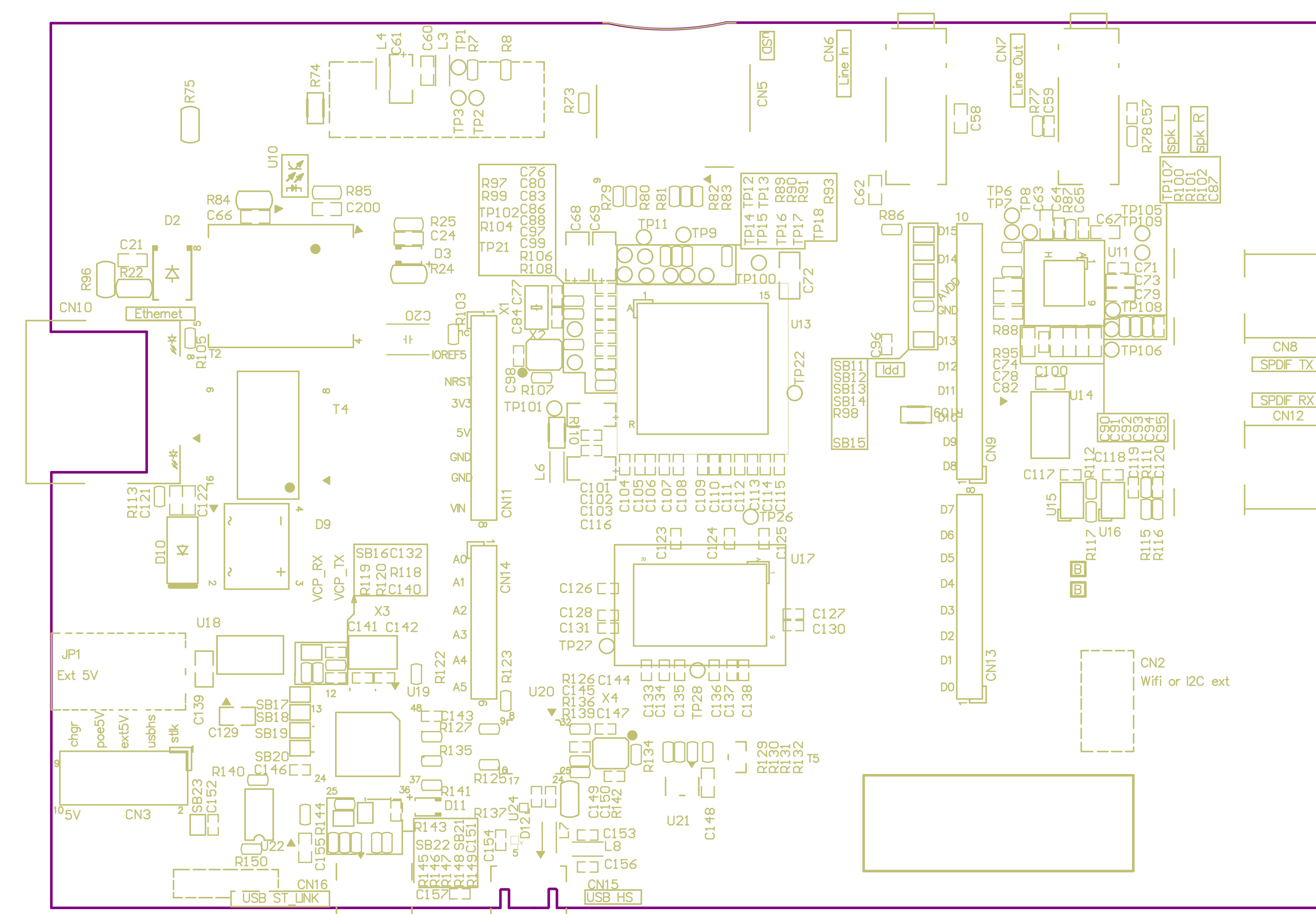



Project: STM32F769I-DISCO		
Layer:	Gerber:	
Variant: F769I	Ref: MB1225	
Date: 01/06/2020	Rev: C	





Project: STM32F769I-DISCO		
Layer: Bottom Solder	Gerber:.GBS	
Variant: F769I	Ref: MB1225	
Date: 01/06/2020	Rev: C	

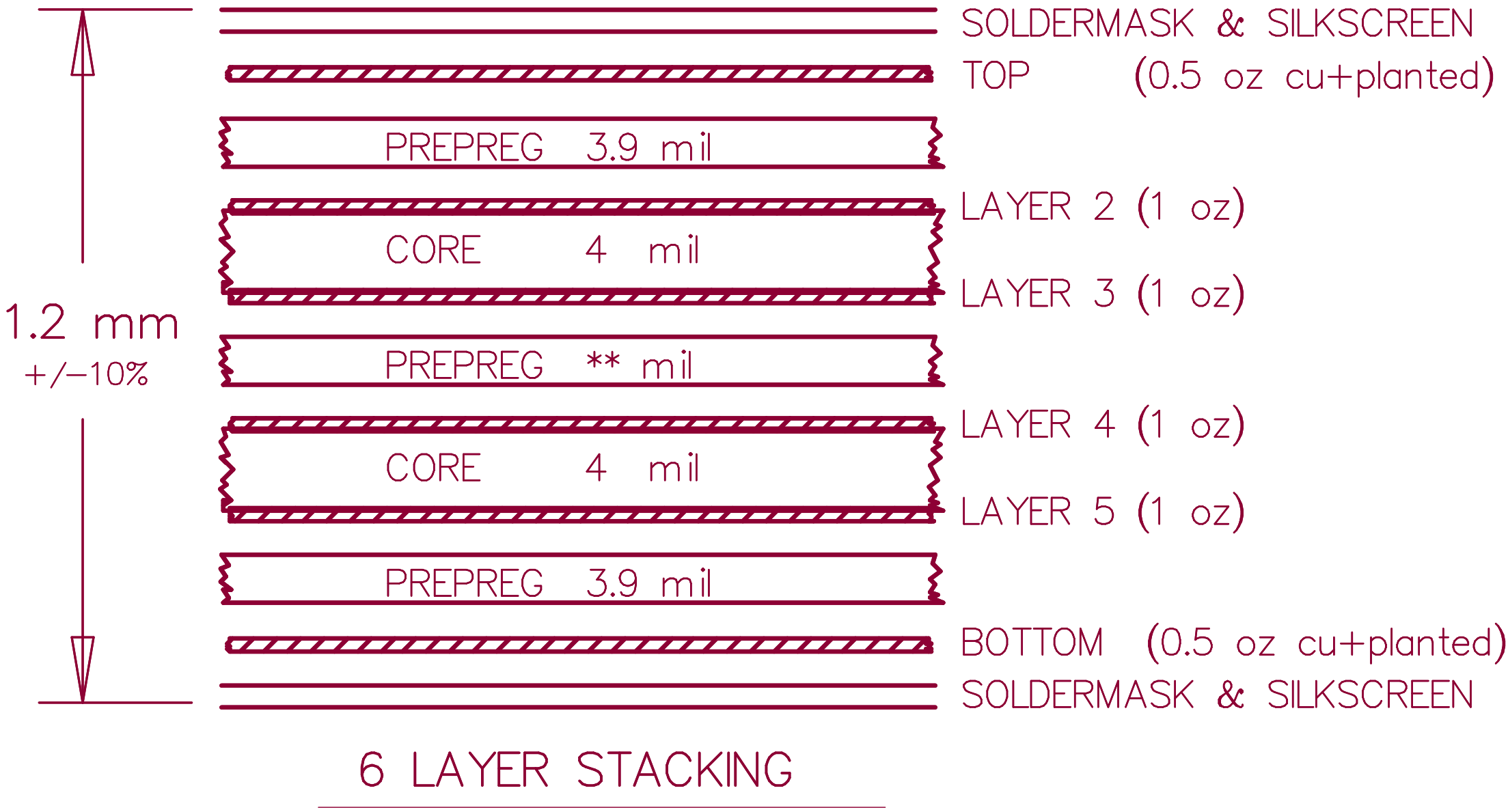


Project: STM32F769I-DISCO		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: F769I	Ref: MB1225	
Date: 01/06/2020	Rev: C	

5 IMPEDANCE TABLE

LAYER	TRACE (mil)	SPACEING (mil)	IMPEDANCE (Single end)	IMPEDANCE (Differential)	TOLERANCE
1,6 4	5.0 4.0	N/A	55 OHM	N/A	+/-10%
1,6	5.1	9.9	N/A	100 OHM	+/-10%
1,6	6.1	8.9	N/A	90 OHM	+/-10%

4 LAYER STUCK-UP

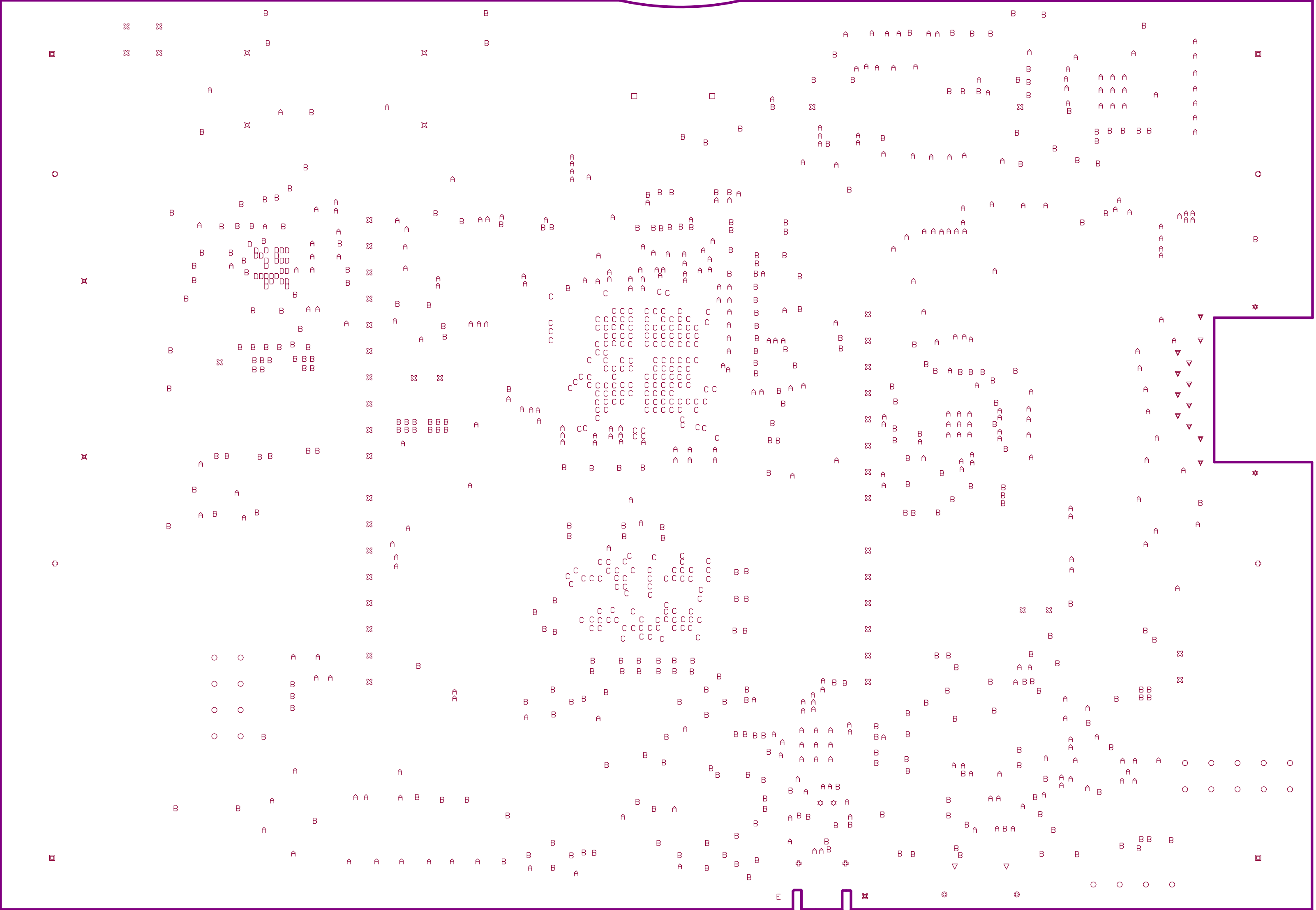


PCB SPECIFICATIONS:

- A. MATERIAL; FR-4, ☒ TG-170 ☐ TG-150 ☐ TG-140
- B. MATERIAL FAMILY; N/A.
- C. SOLDERMASK COLOR; ☐ GREEN ☒ BLUE ☐ RED ☐ BLACK
- D. SILKSCREEN COLOR; ☒ WHITE ☐ YELLOW ☐ BLACK
- E. SURFACE FINISH; ☒ ENIG ☐ IMMERSION SILVER ☐ IMMERSION TIN
☐ HASL ☐ HASL(PB-FREE) ☐ GOLDEN FINGER
- F. IMPEDANCE CONTROL; ☐ NO ☒ YES(SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)
- G. THROUGH VIA; PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL: ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.
- H. STACK-UP; SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.


PCB REQUIREMENTS:

1. THIS BOARD WILL CONFORM TO:
IPC-A-600. CURRENT REV., CLASS II
IPC-6012, CURRENT REV., CLASS II
2. UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING.
ALL HOLES SHALL BE LOCATED WITHIN .003" DIAMETER OF TRUE POSITION.
3. PLATED HOLE WALL THICKNESS SHALL NOT BE LESS THAN .001 INCH MINIMUM
AVERAGE, WITH NO READING LESS THAN .0008 BY COROSS SECTION.
4. MATERIAL FR4 RATING 94V-0 MINIMUM EPOXY GLASS LAMINATE.
5. BOARD SHALL BE LPI SOLDER MASKED OVER BARE COPPER BOTH SIDES PER
IPC-SM-840 CLASS II.
6. SILKSCREEN SHALL BE PERMANENT NON-CONDUCTIVE INK AND WITH NO OVERLAP
ON ANY COMPONENT PAD OR THROUGH HOLE.
7. MFGR, TO LEGIBLY ETCH OR STAMP/SCREEN WITH PERMANENT NON-CONDUCTIVE INK
A. U.L. CODE D. MFGR. LOGO
B. DATE CODE E. SUCCESSFUL ELECTRICAL BOARD TEST.
C. FLAMMABILITY RATING
8. REMOVE THE FLASHS WHICH SMALLER THAN HOLE SIZE.
9. REMOVE ALL SHAPE EDGES AND BURRS .005 MAXIMUM.
10. PLEASE USE THE SUPPLIED IPC 356 NETLIST TO VERIFY BOARD BEFORE
FABRICATING BOARD.



Symbol	Hit Count	Finished Hole Size	Plated	Hole Length	Routed Path Length
D	27	0,15mm	PTH	-	-
☆	2	0,20mm	PTH	-	-
C	219	0,20mm	PTH	-	-
A	354	0,25mm	PTH	-	-
B	347	0,31mm	PTH	-	-
◎	2	0,61mm	PTH	1,30mm	0,69mm
□	2	0,71mm	PTH	-	-
✱	2	0,71mm	PTH	2,21mm	1,50mm
⊕	2	0,76mm	PTH	0,84mm	0,08mm
⊗	1	0,76mm	PTH	1,50mm	0,74mm
▽	2	0,84mm	PTH	-	-
E	1	0,84mm	PTH	1,50mm	0,66mm
▽	12	0,89mm	PTH	-	-
○	22	0,91mm	PTH	-	-
⊗	45	1,02mm	PTH	-	-
✱	2	1,07mm	PTH	1,47mm	0,41mm
✱	4	2,01mm	PTH	-	-
⊕	4	3,51mm	PTH	-	-
⊕	4	4,50mm	PTH	-	-
	1054 Total				

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Project: STM32F769I-DISCO		
Layer: Drill Drawing	Gerber: .DRL	
Variant: F769I	Ref: MB1225	
Date: 01/06/2020	Rev: C	